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In re application of

Title:

MULTI-LAYER POLYMER-SOLDER HYBRID THERMAL

INTERFACE MATERIAL FOR INTEGRATED HEAT

SPREADER AND METHOD OF MAKING SAME

Serial No. 10/607,738

Filed: June 26, 2003

**CONTENTS**: Form PTOL-85(1 pg.), check in the amount of \$1400.00 which represents the Issue Fee Payment, check in the amount of \$300.00 to cover the Publication Fee Payment, check in the amount of \$3.00 for extra copies, 8 Sheets of Formal Drawings, a Communication Concerning Related Applications (1 pg.), and transmittal document (1 pg.).

AMM1:CMG:eno

Mailed: December 22

Docket: 884.832US1

Due Date: December 23, 2005



## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Title:

MULTI-LAYER POLYMER-SOLDER HYBRID THERMAL INTERFACE
MATERIAL FOR INTEGRATED HEAT SPREADER AND METHOD OF MAKING
SAME

Docket No.: 884.832US1

Filed: June 26, 2003

Examiner: Jonathan Johnson

Customer No.: 21186

Commissioner for Patents

Attn: MAIL STOP ISSUE FEE

P.O. Box 1450

Alexandria, VA 22313-1450

Serial No.: 10/607,738

Due Date: December 23, 2005

Group Art Unit: 1725

Confirmation No.: 7568

**Notice of Allowance Date:** 

September 23, 2005

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SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

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Name

Signature

S/N 10/607

PATENT

## <u>D STATES PATENT AND TRADEMARK OFFICE</u>

Applicant:

Sabina J. Houle et al.

Examiner: Jonathan Johnson

Serial No.:

10/607,738

Group Art Unit: 1725

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Title:

MULTI-LAYER POLYMER-SOLDER HYBRID THERMAL INTERFACE MATERIAL FOR INTEGRATED HEAT SPREADER AND METHOD OF

**MAKING SAME** 

Assignee:

**Intel Corporation** 

Customer No. 21186

## COMMUNICATION CONCERNING RELATED APPLICATION(S)

MS Issue Fee Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Applicants would like to bring to the Examiner's attention the following related application(s) in the above-identified patent application:

Serial/Patent No. Filing Date/Issue Date

Attorney Docket

Title

10/612834

June 30, 2003

884.945US1

HEAT DISSIPATING DEVICE WITH

PRESELECTED DESIGNED INTERFACE FOR THERMAL INTERFACE MATERIALS

Continuations and divisionals may be later filed on the cases listed above, or cited to the Examiner in any previous Communication Concerning Related Applications. Applicants request that the Examiner review all continuations and divisionals of the above-listed or previously-cited patent applications before allowing the claims of the present patent application.

> Respectfully submitted, SABINA J. HOULE ET AL. By their Representatives,

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